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Product Change Notice (PCN)

Littelfuse, Inc.
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July 31st, 2025

PCN EIC-1155 Additional Epoxy Mold Compound Qualification for selected 16L SOIC devices

Detailed Description of Change

Littelfuse IXYS Integrated Circuits Division (ICD) would like to inform you about the qualification of an additional EMC (Epoxy Mold Compound) to ensure security of supply for the part numbers summarized in the table below.

The affected part numbers listed below are fully qualified in accordance with established performance and reliability criteria.

Affected PN list
IAA110P
IAA110PTR
CPC1561B
CPC1561BTR

Form, fit, function changes: None
Part number changes: None
Replacement products: N/A
Last time buy: N/A
Effective date: 2025-10-31

The PCN number assigned to this action is **PCN EIC-1155** and must be referenced in any correspondence related to the change.

If you have any other questions or concerns, please contact your local Littelfuse sales representative or Product Manager below for further assistance.

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